Subtractive Process	Material	Mask or Selective Bour	ndary Reference
Wet etching in HF	Glass	Au/Cr	Zhang, J., and T. H. Gong, "Micromachining Technologies for Capillary Electrophoresis Utilizing Pyrex Glass Etching and Bonding," Proceedings of the SPIE—The International Society for Optical Engineering, Vol. 4174, 2000.
Wet etching in KOH	Silicon	Silicon nitride	Feng, GH., and E. S. Kim, "Micropump Based on PZT Unimorph and One-Way Parylene Valves," <i>Journal of Micromechanics and Microengineering</i> , Vol. 14, No. 4, 2004, pp. 429–435.
Wet etching in KOH	Porous silicon	Selectivity to nonporous Si	Steiner, P., A. Richter, and W. Lang, "Using Porous Silicon as a Sacrificial Layer," <i>Journal of Micromechanics and Microengineering</i> , Vol. 3, No. 1, 1993, pp. 32–36.
Wet etching in HF/NH ₄ F	Fused quartz	Sputtered Au/Cr	Jacobson, S. C., A. W. Moore, and J. M. Ramsey, "Fused Quartz Substrates for Microchip Electrophoresis," Analytical Chemistry, Vol. 67, No. 13, 1995, pp. 2059–2063.
Wet etching in HF	Glass	Au/Cr/Au/Cr multilayer	Bu, M., et al., "A New Masking Technology for Deep Glass Etching and Its Microfluidic Application," Sensors and Actuators, A: Physical, Vol. 115, No. 2-3, 2004, pp. 476–482.
Wet etching in TMAH	Silicon	TEOS	Ko, H. S., C. W. Liu, and C. Gau, "Novel Fabrication of a Pressure Sensor with Polymer Material and Evaluation of Its Performance," Journal of Micromechanics and Microengineering, Vol. 17, No. 8, 2007, pp. 1640–1648.
Wet etching in EDP	Silicon	Crystallographic boundarie	Parviz, B. A., and K. Najafi, "A Geometric Etch-Stop Technology for Bulk Micromachining," Journal of Micromechanics and Microengineering, Vol. 11, No. 3, 2001, pp. 277–282.
Wet etching in iron chloride	Copper	Photoresist	Nguyen, NT., and X. Huang, "Miniature Valveless Pumps Based on Printed Circuit Board Technique," Sensors and Actuators, A: Physical, Vol. 88, No. 2, 2001, pp. 104–111.
Electrochemical machining	Copper, stain- less steel	Photoresist	Datta, M., "Fabrication of an Array of Precision Nozzles by Through-Mask Electrochemical Micromachining," Journal of the Electrochemical Society, Vol. 142, No. 11, 1995, pp. 3801–3805.
Plasma etching in CF ₄ /Ar or CF ₄ /O ₂	Glass	Evaporated Ni	Zeze, D. A., et al., "Reactive Ion Etching of Quartz and Pyrex for Microelectronic Applications," <i>Journal of Applied Physics</i> , Vol. 92, No. 7, 2002, pp. 3624–3629.
Plasma etching in C4F8 or CHF3	Glass	Bonded silicon wafer	Akashi, T., and Y. Yoshimura, "Deep Reactive Ion Etching of Borosilicate Glass Using an Anodically Bonded Silicon Wafer as an Etching Mask," <i>Journal of Micromechanics and Microengineering</i> , Vol. 16, No. 5, 2006, pp. 1051–1056.
Plasma etching in SF ₆ /O ₂	PDMS/PMHS	Sputtered Al	Szmigiel, D., et al., "Deep Etching of Biocompatible Silicone Rubber," <i>Microelectronic Engineering</i> , Vol. 83, No. 4-9, 2006, pp. 1178-1181.
or CF ₄ /O ₂ Plasma etching in SF ₆ /O ₂	PDMS	SU-8	Plecis, A., and Y. Chen, "Improved Glass-PDMS-Glass Device Technology for Accurate Measurements of Electro-Osmotic Mobilities," <i>Microelectronic Engineering</i> , Vol. 85, No. 5-6, 2008, pp. 1334–1336.
Plasma etching in CF ₄ /O ₂	PDMS	Evaporated Al	Garra, J., et al., "Dry Etching of Polydimethylsiloxane for Microfluidic Systems," Journal of Vacuum Science and Technology A, Vol. 20, No. 3, 2002, pp. 975–982.
Plasma etching in CF ₄ /Ar, CHF ₃ /Ar	Quartz	SU-8	Chen, H., and C. Fu, "An Investigation into the Characteristics of Deep Reactive Ion Etching of Quartz Using SU-8 as a Mask," <i>Journal of Micromechanics and Microengineering</i> , Vol. 18, No. 10, 2008, p. 105001.
Plasma etching in O ₂	Polyimide	PECVD silicon nitride	Agarwal, N., et al., "Optimized Oxygen Plasma Etching of Polyimide Films for Low Loss Optical Waveguides," Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, Vol. 20, 2002, No. 5, pp. 1587–1591.
Plasma etching in O ₂	Parylene	Photoresist	Meng, E., and YC. Tai, Parylene Etching Techniques for Microfluidics and BioMEMS, Miami Beach, FL: Institute of Electrical and Electronics Engineers Inc., 2005.
Plasma etching in SF ₆ /Ar	Glass	Electroplated nickel	Park, J. H., et al., "Deep Dry Etching of Borosilicate Glass Using SF6 and SF6/Ar Inductively Coupled Plasmas," Microelectronic Engineering, Vol. 82, No. 2, 2005, pp. 119-128.
Plasma etching	Polyimide	Copper	Rossier, J. S., et al., "Plasma Etched Polymer Microelectrochemical Systems," Lab on a Chip, Vol. 2, No. 3, 2002, pp. 145–150.
Plasma etching in micro- wave CF ₄ /O ₂	PDMS	Nickel	Sung, J. H., et al., "Dry Etching of Polydimethylsiloxane Using Microwave Plasma," Journal of Micromechanics and Microengineering, Vol. 19, No. 9, 2009, p. 095010.
Plasma etching in SF ₆	Glass	Electroplated nickel	Li, X., T. Abe, and M. Esashi, "Deep Reactive Ion Etching of Pyrex Glass Using SF6 Plasma," Sensors and Actuators, A: Physical, Vol. 87, No. 3, 2001, pp. 139-145.
Plasma etching	Glass	Amporphous silicon	Kutchoukov, V. G., et al., "Fabrication of Nanofhuidic Devices Using Glass-to-Glass Anodic Bonding," Sensors and Actuators, A: Physical, Vol. 114, No. 2-3, 2004, pp. 521–527.
Deep reactive ion etching	Silicon	Thermally grown silicon di	
Vapor-phase etching in XeF2	Silicon dioxide	SiO ₂ , Si ₃ N ₄ , SiC	Winters, H. F., and J. W. Coburn, "The Etching of Silicon with XeF2 Vapor," Applied Physics Letters, Vol. 34, No. 1, 1979, pp. 70-73.
Laser ablation	Polyimide	(direct-write)	Yin, H., et al., "Microfluidic Chip for Peptide Analysis with an Integrated HPLC Column, Sample Enrichment Column, and Nanoelectrospray Tip," <i>Analytical Chemistry</i> , Vol. 77, No. 2, 2005, pp. 527–533.
Laser ablation (CO ₂)	PMMA	(direct-write)	Snakenborg, D., H. Klank, and J. P. Kutter, "Microstructure Fabrication with a CO2 Laser System," Journal of Micromechanics and Microengineering, Vol. 14, No. 2, 2004, pp. 182–189.
Laser ablation (excimer)	Polycarbonate		r, M., et al., "A Modular Structured, Planar Micro Pump with No Moving Part (NMP) Valve for Fluid Handling in Microanalysis s," <i>2nd Annual International IEEE-EMBS Special Topic Conference on Microtechnologies in Medicine and Biology</i> , 2002
Laser ablation	PDMS	(direct-write)	Liu, HB., and HQ. Gong, "Templateless Prototyping of Polydimethylsiloxane Microfluidic Structures Using a Pulsed CO2 Laser," <i>Journal of Micromechanics and Microengineering</i> , Vol. 19, No. 3, 2009, p. 037002.
Laser ablation (femtosecond)	PMMA,	(direct-write)	Gomez, D., et al., "Femtosecond Laser Ablation for Microfluidics," Optical Engineering, Vol. 44, No. 5, 2005, p. 51105-1
Proton beam writing	polyimide, glass PMMA	(direct-write)	Mahabadi, K. A., et al., "Fabrication of PMMA Micro- and Nanofluidic Channels by Proton Beam Writing: Electrokinetic and Morphological Characterization," Journal of Micromechanics and Microengineering, Vol. 16, No. 7, 2006, pp. 1170–1180.
Abrasive jet milling	Glass	Metal	Belloy, E., et al., "The Introduction of Powder Blasting for Sensor and Microsystem Applications," Sensors and Actuators A: Physical, Vol. 84, No. 3, 2000, pp. 330–337.
Abrasive jet of Al ₂ O ₃	Glass	PDMS	Sayah, A., et al., "Fabrication of Microfluidic Mixers with Varying Topography in Glass Using the Powder-Blasting Process," <i>Journal of Micromechanics and Microengineering</i> , Vol. 19, No. 8, 2009, p. 085024.
Abrasive jet of SiC	Stainless steel		Lomas, T., et al., "A Precision Hot Embossing Mold Fabricated by High-Resolution Powder Blasting with Polydimethylsiloxane and SU-8 Masking Technology," <i>Journal of Micromechanics and Microengineering</i> , Vol. 19, No. 3, 2009, p. 035002.
Chemical-mechanical polishing	Polycarbonate, PMMA	(not applicable)	Zhong, Z. W., Z. F. Wang, and B. M. P. Zirajutheen, "Chemical Mechanical Polishing of Polycarbonate and Poly Methyl Methacrylate Substrates," <i>Microelectronic Engineering</i> , Vol. 81, No. 1, 2005, pp. 117–124.
Razor cutting	Various polymer films	(direct-write)	Bartholomeusz, D. A., R. W. Boutte, and J. D. Andrade, "Xurography: Rapid Prototyping of Microstructures Using a Cutting Plotter," <i>Journal of Microelectromechanical Systems</i> , Vol. 14, No. 6, 2005, pp. 1364–1374.